

RoHS

COMPLIANT

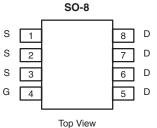
HALOGEN

FREE

Vishay Siliconix

N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
20	0.006 at V _{GS} = 10 V	20 ^e	27.5 nC			
20	0.007 at V_{GS} = 4.5 V	20 ^e	27.5110			

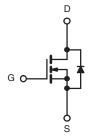


FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested ٠
- Compliant to RoHS Directive 2002/95/EC •

APPLICATIONS

- · Low-Side MOSFET for Synchronous Buck - Game Machine
 - PC



Ordering Information: Si4114DY-T1-E3 (Lead (Pb)-free) Si4114DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

ABSOLUTE MAXIMUM RATIN	IGS T _A = 25 °C,	unless other	wise noted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 16		
Continuous Drain Current (T _J = 150 °C)	$T_{C} = 25 °C$ $T_{C} = 70 °C$ $T_{A} = 25 °C$ $T_{A} = 70 °C$	- I _D -	20 ^e 18.2 15.2 ^{b, c} 12.1 ^{b, c}		
Pulsed Drain Current		I _{DM}	50	A	
Continuous Source-Drain Diode Current	T _C = 25 °C T _A = 25 °C	I _S	5.1 2.2 ^{b, c}		
Single Pulse Avalanche Current L = 0.1 mH		I _{AS}	30		
Avalanche Energy	L = 0.1 mm	E _{AS}	45	mJ	
Maximum Power Dissipation	$T_{C} = 25 °C$ $T_{C} = 70 °C$ $T_{A} = 25 °C$ $T_{A} = 70 °C$	- P _D -	5.7 3.6 2.5 ^{b, c} 1.6 ^{b, c}	w	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	39	50	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	18	22	0/10		

Notes:

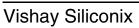
a. Based on $T_C = 25 \ ^{\circ}C$.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 85 °C/W.

e. Package limited.





Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					1		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 050 4		19		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.3			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0		2.1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 16 V$			± 100	nA	
		$V_{DS} = 20 V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	IDSS	V_{DS} = 20 V, V_{GS} = 0 V, T_{J} = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		V _{GS} = 10 V, I _D = 10 A		0.0049	0.006		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 7 \text{ A}$		0.0056	0.007	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 10 A		55		S	
Dynamic ^b	1 1					I	
Input Capacitance	C _{iss}			3700		pF	
Output Capacitance	C _{oss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		745			
Reverse Transfer Capacitance	C _{rss}			315			
Total Gate Charge		$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		62	95		
	Q_g			27.5	42		
Gate-Source Charge	Q _{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_D = 10 A		8.0		- nC	
Gate-Drain Charge	Q _{gd}			6.0			
Gate Resistance	Rg	f = 1 MHz	0.15	0.7	1.4	Ω	
Turn-On Delay Time	t _{d(on)}			30	55	-	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2 Ω		13	25		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D} \cong \text{5}$ A, V_GEN = 4.5 V, R_g = 1 Ω		60	100		
Fall Time	t _f			30	55		
Turn-On Delay Time	t _{d(on)}			13	25	ns	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2 Ω		9	18		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}{\cong}5$ A, V_GEN = 10 V, R_g = 1 Ω		38	65		
Fall Time	t _f			8	16		
Drain-Source Body Diode Characterist	ics			1			
Continuous Source-Drain Diode Current	ا _S	T _C = 25 °C			5.1	^	
Pulse Diode Forward Current ^a	I _{SM}				50	A	
Body Diode Voltage	V _{SD}	I _S = 2 A		0.71	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			26	50	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 10.0 d/dt = 100.0/trace		16	30	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{ T}_J = 25 ^\circ\text{C}$		13			
Reverse Recovery Rise Time				13		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

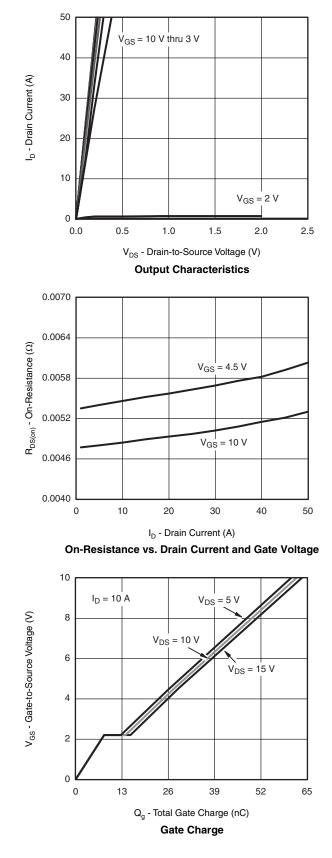
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

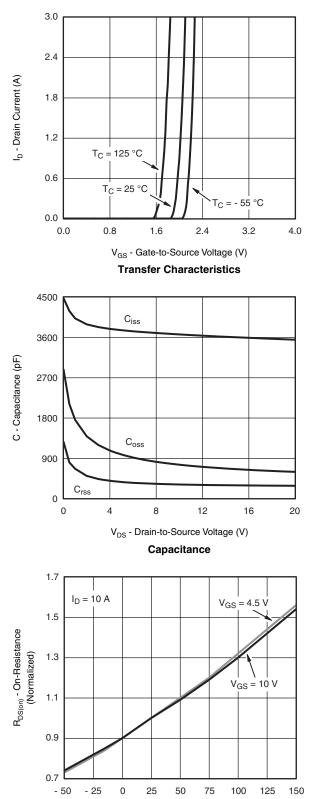




Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





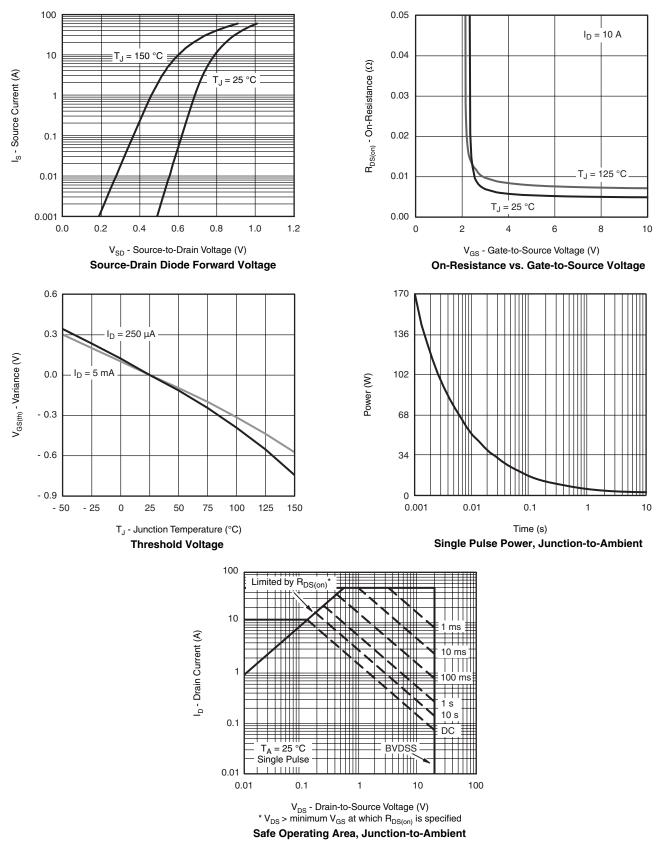
Document Number: 68394 S09-0764-Rev. B, 04-May-09 T_{.1} - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

Vishay Siliconix



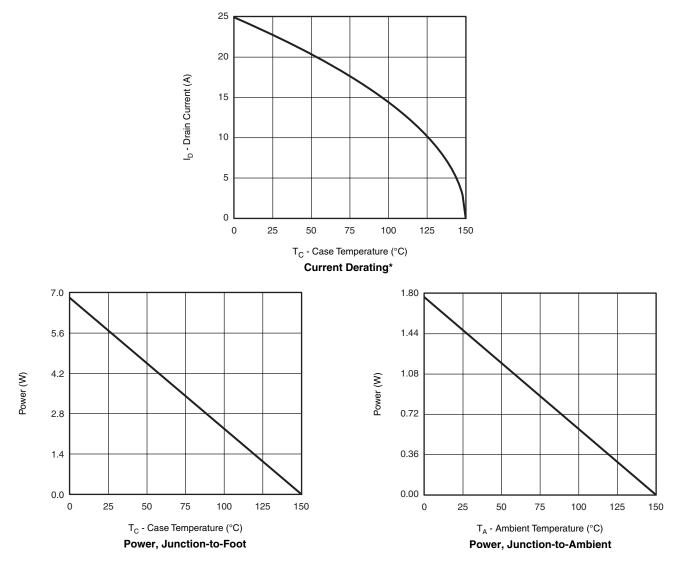
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Si4114DY Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

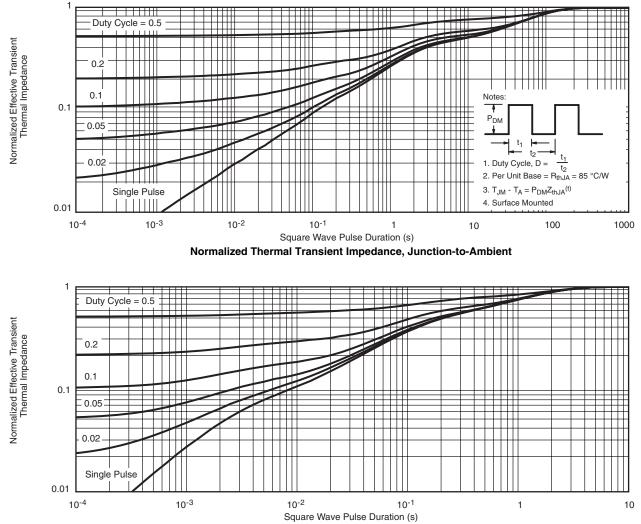


* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

Vishay Siliconix



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?68394.



Package Information

Vishay Siliconix

SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					

Application Note 826

Vishay Siliconix



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index



Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Vishay manufacturer:

Other Similar products are found below :

614233C 648584F IRFD120 JANTX2N5237 2N7000 FCA20N60_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C IPS70R2K0CEAKMA1 BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384 NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956 NTE2911 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B